



Docket No.: 43890-542

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of

Toshiaki TAKENAKA, et al.

Serial No.: 09/937,719

Filed: January 03, 2002

For: PRINTING PLATE, AND PRINTING METHOD USING THE SAME

Group Art Unit: 2854

Examiner: Stephen R. Funk

*fee OK*

*#9/a*  
*5-2-03*  
*L. Spruell*

**AMENDMENT**

Commissioner for Patents  
Washington, DC 20231

Sir:

In response to the Office Action dated January 30, 2003, having a three-month shortened statutory period for response set to expire on April 30, 2003, reconsideration of the above-identified application is respectfully requested in view of the following amendment and remarks.

05/05/2003 LSPRUELL 00000001 500417 09937719

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**IN THE SPECIFICATION**

Please replace the paragraph beginning on page 3, line 1 with the following paragraph:

A description is further given to the method for filling conductive paste 24 with reference to Fig. 9, Fig. 10 and Fig. 11(a) to Fig. 11(g). A squeegeeing method is used to fill conductive paste 24. However, since mask films 22a and 22b designed specifically for use with prereg sheet 21 are put in place, mask 2, which is formed of stainless steel,

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